Docket No.:

SI-0036

## **DECLARATION AND POWER OF ATTORNEY**

As a below named inventor, I hereby decl	are that:		
My residence, post office and citizenship a	are as stated below next to my name	,	
I believe I am the original, first and sole i are listed below) of the subject matter clapacket calls in mobile commun	timed and for which a patent is soug	ght on the invention entitl	
[X] is attached hereto [ ] was filed o amended on	n as Application Se		and was
I hereby state that I have reviewed and us any amendment referred to above.	nderstand the contents of the above	identified specification, is	ncluding the claims, as amended by
I acknowledge the duty to disclose inform Federal Regulations, Section 1.56(a).	nation which is known to me to be a	material to patentability in	accordance with Title 37, Code of
I hereby claim foreign priority benefits certificate, or 365(a) of any PCT internat listed below and have also identified below international application having a filing da	ional application which designated a w, by checking the box, any foreign a	it least one country other application for patent or it	than the United States of America,
Prior Foreign Application(s): Number	Country	Foreign Filing Month/Day/Ye	Date ear
44942/2002	Korea	7/30/2002	
55628/2002	Korea	9/13/2002	
I hereby claim the benefit under 35 U.S.C.	. 119(e) of any United States provision	onal application(s) listed b	elow.
Application Number(s)	Filing Date(Month/I	Day/Year)	
I hereby claim the benefit under 35 U.s. designating the United States of America disclosed in the prior United States or P acknowledge the duty to disclose informathe filing date of the prior application and	S.C. 120 of any United States app Listed below and, insofar as the su CT international application in the tion which is material to patentabilit	olication(s), or 365(c) of object matter of each of t manner provided by the type as defined in 37 CFR 1.	any PCT international application he claims of this application is not first paragraph of 35 U.S.C. 112, I 56 which became available between in.
Prior U. S. Application or PCT Patent Number	Filing Date(Month/Day/Year)		nt Number(if application)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s): Daniel Y.J. Kim, Registration No. 36,186; Mark L. Fleshner, Registration No. 34,596; Carl R. Wesolowski, Registration No. 40,372; John C. Eisenhart, Registration No. 38,128; Donald R, McPhail, Registration No. 35,811; Carol L. Druzbick, Registration No. 40,287; Anthony H. Nourse, Registration No. 46,121; Laura L. Lee, Registration No. 48,752; Rene A. Vazquez, Registration No. 38,647; Timothy M. Speer, Registration No. 47,355; Samuel W. Ntiros, Registration No. 39,318; Mark R. Buscher, Registration No. 35,006; Daniel H. Sherr, Registration No. 46,425; Tyler S. Brown, Registration No. 36,465; John J. Ciccozzi, Registration No. 48,984; Steven J. Helrner, Registration No. 40,475; and Mark E. Olds, Registration No. 46,507, all of

with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark

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Office connected therewith, and all further correspondence should be addressed to them. Full name of solo or first inventor: So Hyun PARK Date: Jun 30, 2003 Inventor's signature: Mailing Address: 111-1001, Samick-Apartment, Siheung 4-dong, Geumcheon-gu, Seoul, Republic of Korea 153-034 Citizenship: Republic of Korea Residence Address (only if different from mailing address): Full name of joint inventor(s): Inventor's signature: Date: Mailing Address: Citizenship: Residence Address (only if different from mailing address): Full name of joint inventor(s): Inventor's signature: Date: Mailing Address: Citizenship: Residence Address

(only if different from mailing address):